AMENDMENTS TO THE SPECIFICATION

Please replace paragraph 4 of page 2, beginning on line 15 on page 2, with the following amended paragraph:

At this time, because the router cut line 7 is wider than the power supply line 5, when the printed circuit boards 1a and 1b are separated, the power supply line 5 is removed so that each bonding pad 3 and ball pad 4 ~~is electrically short~~ and only the lead-in wired 6 remain.

Please replace paragraph 6, beginning on line 23 on page 3-4, with the following amended paragraph:

To achieve these and other advantages and in accordance with the purpose of the present invention, as embodied and broadly described herein, there is provided a plating method for a printed circuit board including~~: A plating method for a printed circuit board comprising:~~ a first step of providing a substrate having a plurality of connection pads and circuit patterns connected to the connection pads; a second step of using some of the circuit patterns provided on a surface of the substrate as a power connection portion and connecting the power connection portion to an external power source; a third step of covering a surface of the substrate excepting the connection pads with a plating resistance

resist to sh8ield it; a fourth step of supplying power to the connection pad through the power connection portion and forming a gold-plated layer on the connection pad; and a fifth step of ~~making~~ disconnecting the power connection portion ~~and~~ from the external power source ~~to be electrically short~~.

Please replace paragraph 3 of page 4, beginning on line 20 on page 4, with the following amended paragraph:

In the plating method for a printed circuit board of the present invention, in the third step, the plating resistance resist is coated at the surface of the substrate with the electrolyte layer formed thereon, and the fifth step includes: removing the electrolyte layer and the plating resistance resist; and coating a photoresist at the surface of the electrolyte layer and the plating resistance resist-removed substrate to cover the power connection portion ~~to make power short~~.

Please replace paragraph 1 of page 5, beginning on line 1 on page 5, with the following amended paragraph:

To achieve the above objects, there is also provided a plating method for a printed circuit board including: a first step of providing a substrate having a plurality of bonding pads and ball pads at both sides thereof and a circuit pattern to which the bonding pads and the ball pads are connected; a second step of using some of the

circuit patterns provided at the surface of the substrate as first and second power connection portions and connecting the first power connection portion to an external power source; a third step of covering the surface of the substrate with the ball pad formed thereon with a plating resistance resist to shield it; a fourth step of supplying power to the bonding pad through the first power connection portion to form a gold-plated layer on the bonding pad; a fifth step of ~~making~~ disconnecting the connection between the first power connection portion and the external power source ~~to be electrically short~~; a sixth step of connecting the second power connection portion to the external power source and coating a plating resistance resist at the surface of the substrate with the ball pad formed thereon to shield it; a seventh step of supplying power to the ball pad through the second power connection portion to form a gold-plated layer on the ball pad; and an eighth step of ~~making~~ disconnecting the connection between the second power connection portion and the external power source ~~to be electrically short~~.

Please replace paragraph 3 of page 5, beginning on line 25 on page 5-6, with the following amended paragraph:

In the plating method for a printed circuit board of the present invention, the fifth step includes: removing the electrolyte layer and the plating resistance resist; and

coating a photoresist at the surface of the electrolyte layer and the plating resistance resist-removed substrate to cover the first power connection portion ~~to make power short~~.

Please replace paragraph 2 of page 6, beginning on line 10 on page 6, with the following amended paragraph:

In the plating method for a printed circuit board of the present invention, the eighth step includes: removing the plating resistance resist and the electrolyte layer; and covering the second power connection portion with a photoresist ~~to make the second power connection to be short electrically~~.

Please replace paragraph 4 of page 8, beginning on line 14 on page 8, with the following amended paragraph:

Next, the metal layer 56 and the metal-plated layer 60 are selectively removed to form a circuit pattern 62. That is, the circuit patterns 62 are formed at both surfaces of the substrate 50 through a general exposure/development process and an etching process, and some of the circuit patterns 62 are used as a bonding pad 64 electrically connected to a semiconductor chip and some other circuit patterns are sued as a ball pad 66 electrically

connected to another printed circuit board. In general, the ball pad 66 is formed at the opposite side of the side where the

bonding pad ~~65~~ 64 is formed.

Please replace paragraph 1 of page 9, beginning on line 1 on page 9, with the following amended paragraph:

A solder ball is attached to the ball pad 66 for connection with a different printed circuit board, and the ball pad 66 is electrically connected to the circuit patter 62 formed at the through hole 58 by the connection pattern 68 (refer to Figure 4C).

Please replace paragraph 2 of page 11, beginning on line 6 on page 11, with the following amended paragraph:

After the gold-plated layer 82 is completely formed at the bonding pad 64, the plating resistance resist 80 and the electrolyte layer 78 formed at the surface where the ball pad 66 is provided are removed. And then the first power connection portion 72 is covered with the photoresist 70 to make it not exposed ~~electrically short~~ (refer to Figures 4I, 5C and 5D).

Please replace paragraph 8 of page 11, beginning on line 24 on page 11-12, with the following amended paragraph:

The external power (P) is supplied to the electrolyte layer 88 and applied to the ball pad 66 through the second power connection portion 74 connected to the electrolyte layer 88 and the circuit pattern 62 formed at the through hole 58 and the connection ~~pad~~ pattern 68.

Please replace paragraph 1 of page 12, beginning on line 3 on page 12, with the following amended paragraph:

After the gold-plated layer 92 is formed at the ball pad 66, the plating resistance resist 90 and the electrolyte layer 88 are removed and the second power connection portion 74 is covered with the photoresist 70 so that the second power connection portion 74 can be electrically ~~short~~ not exposed and insulated within the substrate.